



—Copper Clad Laminate— “3layer FCCL”

Example of use

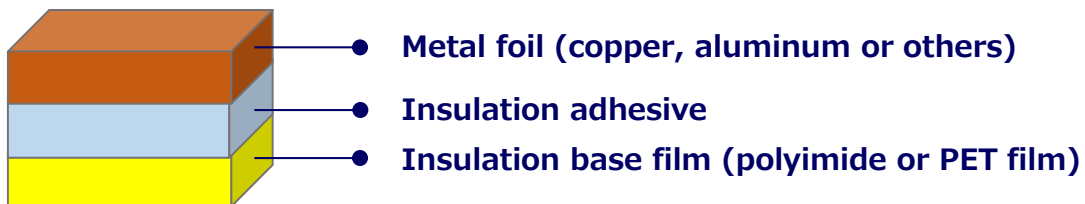
- Mobile devices (mobile phone, Tablet PC and others)
- HDD · DSC
- Substrate for LED · For automobile applications



Characteristics

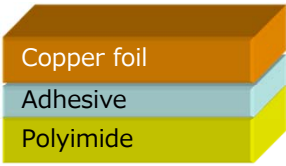
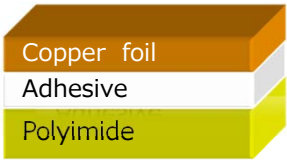
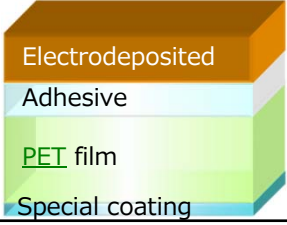
- FCCL with internally designed polyimide resin coated on base film such as polyimide, and laminated copper foil.
- Product design with unique characteristics are available as per customer request by changing base material and copper foil.

Product structure



※Double-sided FCCL is also available.

Product Properties

Item		Condition	Unit	LC	LE(P)	LCB	L60R	LSPGS
Characteristic		—	—	For general purpose	High Tg	Black	White	Transparent adhesive
Product structure		—	—					
180° Peel strength	MD	Normal state	N/cm	11.0	7.5	9.0	10.0	8.0
Dimensional stability	0.5hr/150°C	MD	%	-0.08	-0.15	-0.15	-0.10	*-0.18
		TD		+0.08	+0.02	+0.08	-0.05	*0.06
Solder heat resistance		—	°C	300	300	300	300	190
Adhesive Tg		—	°C	42	143	42	50	30
Adhesive elasticity		Norma state	GPa	0.3	4.0	0.4	1.5	0.7

*0.5hr/125°C

※Double-sided structures are also available.



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The data in this document are measured values, not for guaranteed.